



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-12-17
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Andrea Casali	Representative Title	APG MD CHAMPION
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L99PM62GXP	G6EH*UK19AB1	A	MU1A	2013-12-17
Amount	UoM	Unit type	ST ECOPACK Grade	
484.70	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	10.3x7.50x2.28	36	flat	
Comment				

Material Composition Declaration						Mfr Item Name	G6EH*UK19AB1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	14.657	mg	supplier	die	Silicon (Si)	7440-21-3		14.014	mg	956130	28913
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.092	mg	6277	190
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.092	mg	6277	190
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.112	mg	7641	231
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.022	mg	1501	45
die (s)				supplier	passivation	Indium Tin oxide (In2O3.SnO2)	50926-11-9		0.216	mg	14737	446
die (s)				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.008	mg	546	17
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.021	mg	1433	43
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.071	mg	4844	146
die (s)				supplier	polymer die coating	Polymer resist (Black resist)	Proprietary		0.009	mg	614	19
Leadframe	Copper & its alloys	160.882	mg	supplier	alloy	Copper (Cu)	7440-50-8		154.646	mg	961239	319055
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		3.637	mg	22607	7504
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.219	mg	1361	452
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.190	mg	1181	392
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		2.190	mg	13612	4518
Die attach		9.208	mg	JIG R	glue or tape	Lead (Pb)	7439-92-1	7a-Lead in high me	8.978	mg	975022	38523
Die attach				supplier	glue or tape	Silver (Ag)	7440-22-4		0.138	mg	14987	285
Die attach				supplier	glue or tape	Tin (Sn)	7440-31-5		0.092	mg	9991	190
Bonding wire		1.389		supplier	wire	Gold (Au)	7440-57-5		1.376	mg	990641	2839
Bonding wire				supplier	wire	Copper (Cu)	7440-50-8		0.008	mg	5760	17
Bonding wire				supplier	wire	Palladium (Pd)	7440-05-3		0.004	mg	2880	8
Bonding wire				supplier	wire	Platinum (Pt)	7440-06-4		0.001	mg	720	2
encapsulation		292.589	mg	supplier	mold compound	Phenol Resin	205830-20-2		11.703	mg	39998	24145
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		8.777	mg	29998	18108
encapsulation				supplier	mold compound	epoxy resin	Proprietary		8.777	mg	29998	18108
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.585	mg	1999	1207
encapsulation				supplier	mold compound	silica vitreous	60676-86-0		262.747	mg	898007	542082
connections coating	Solder	5.973	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.973	mg	1000000	12323